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(12) **United States Design Patent**
Chen et al.

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(54) **HEAT DISSIPATING MODULE**

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(**) Term: **14 Years**

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(51) **LOC (9) Cl.** **13-03**

(52) **U.S. Cl.** **D13/179**

(58) **Field of Classification Search** D13/179;
165/80.3, 104.33, 151, 122, 185; 257/706,
257/707, 718-722; 361/687, 695, 697, 700,
361/702, 704, 709, 710, 711, 719

See application file for complete search history.

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(57) **CLAIM**

The ornamental design for a heat dissipating module, as
shown and described herein.

DESCRIPTION

FIG. 1 is a perspective view of a heat dissipating module
showing our new design;

FIG. 2 is a front elevational view thereof;

FIG. 3 is a rear elevational view thereof;

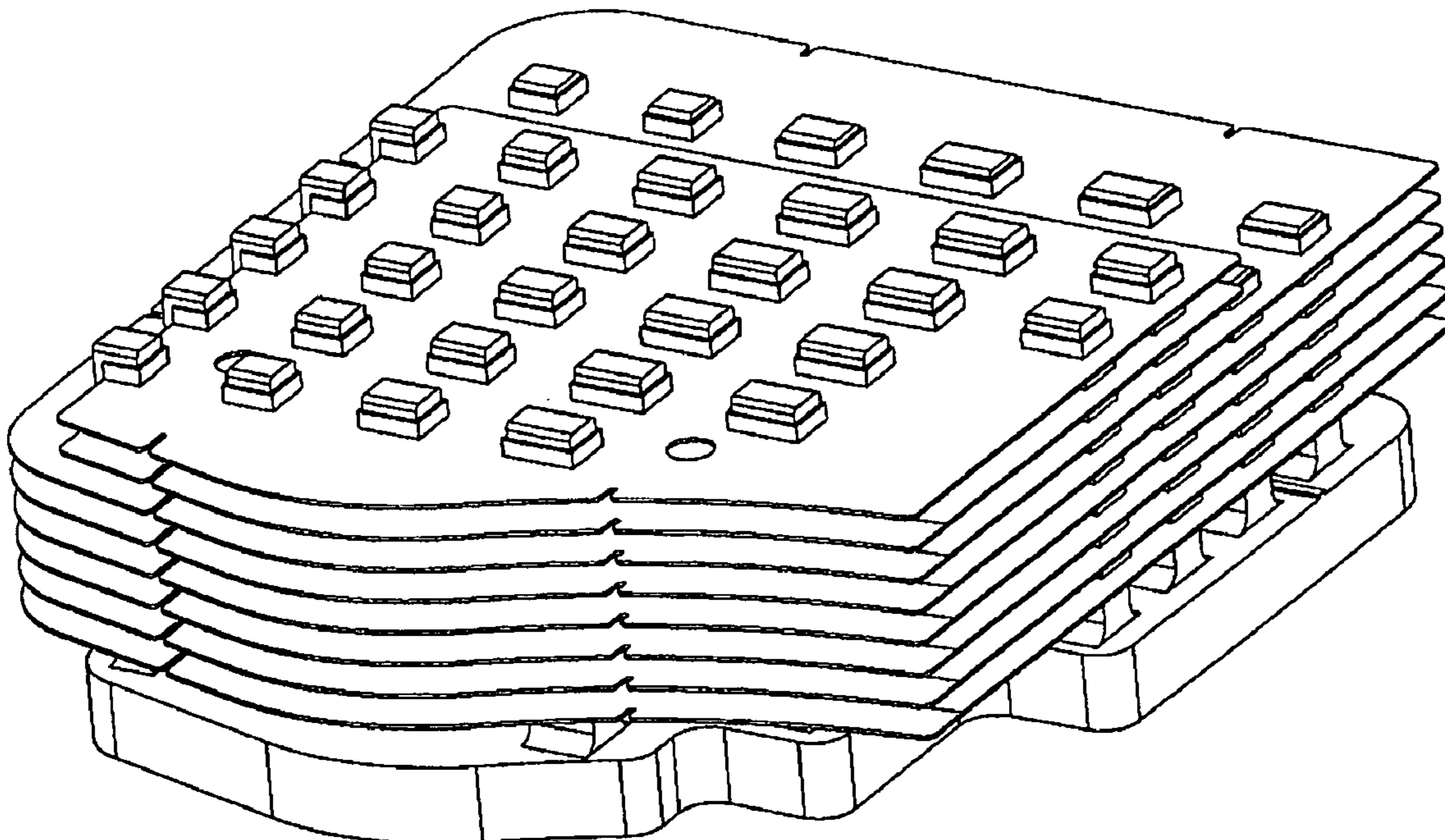
FIG. 4 is a left side elevational view thereof; and

FIG. 5 is a right side elevational view thereof.

FIG. 6 is a top plan view thereof; and,

FIG. 7 is a bottom plan view thereof.

1 Claim, 5 Drawing Sheets



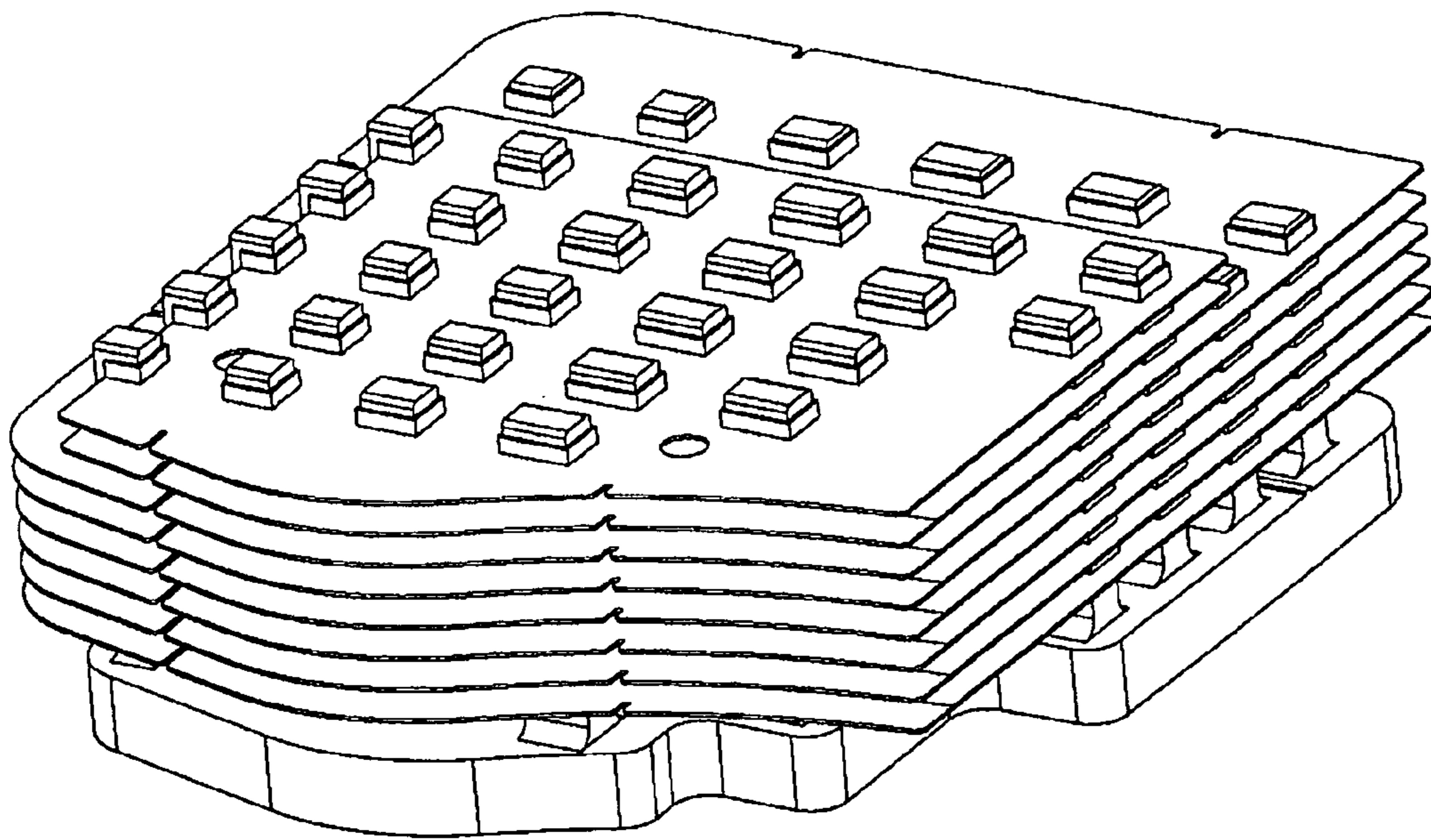


FIG. 1

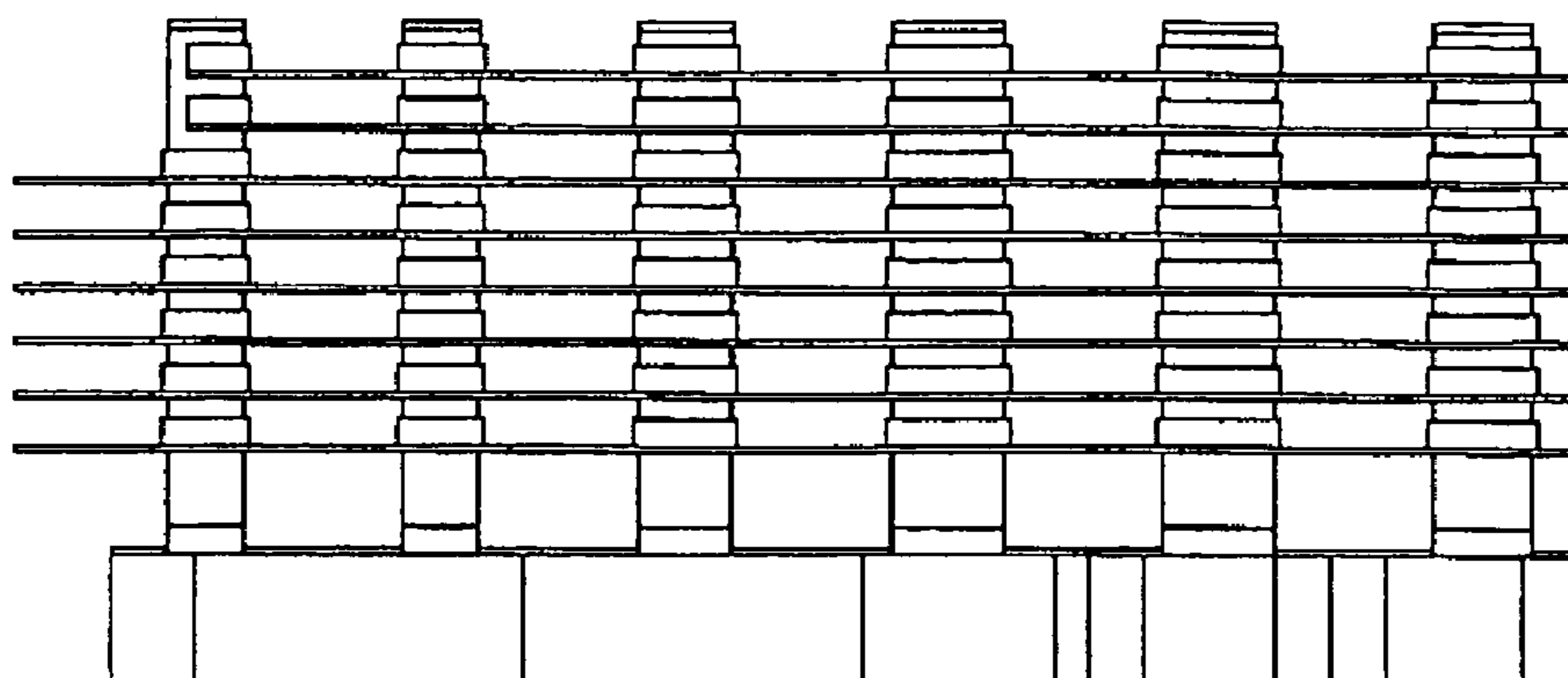


FIG. 2

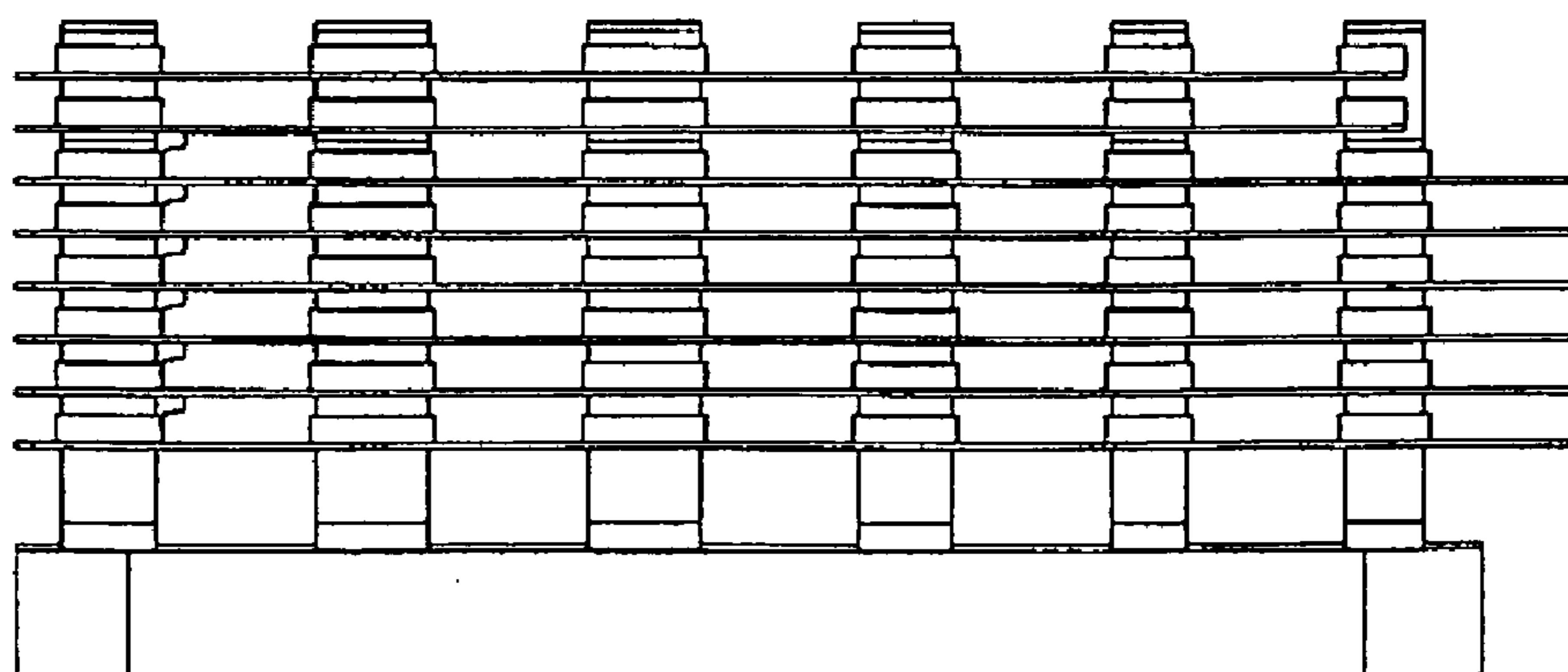


FIG. 3

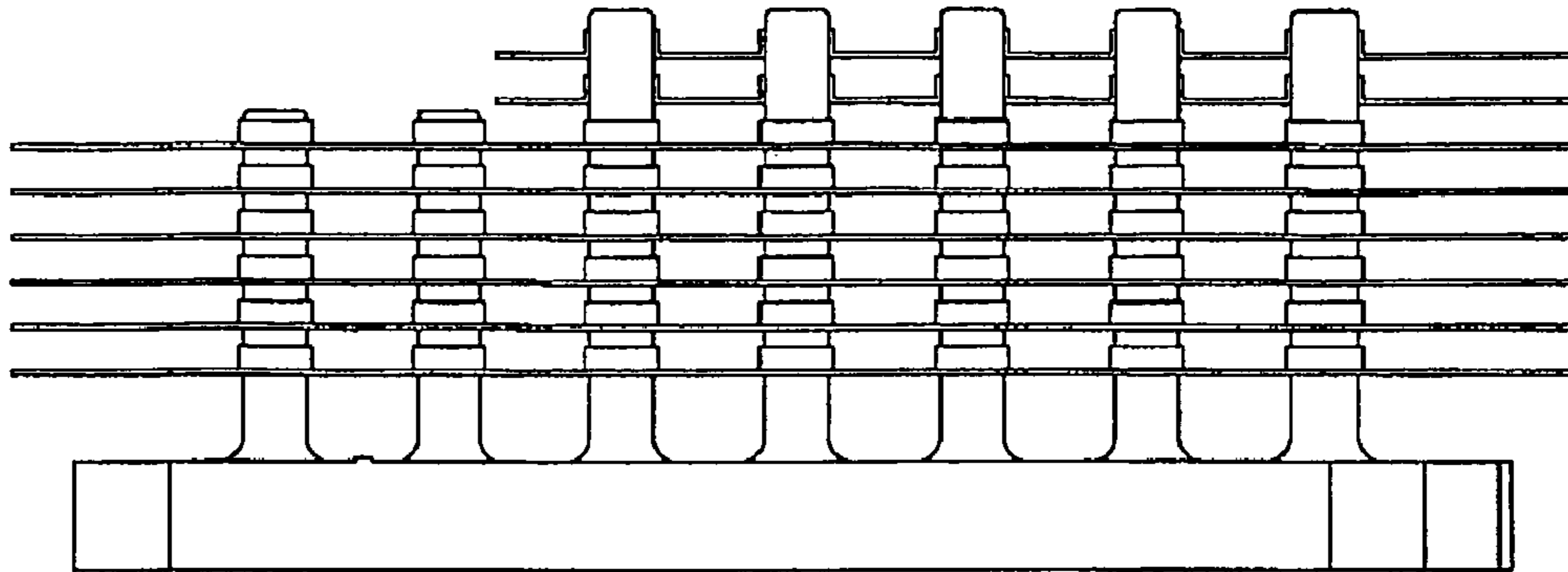


FIG. 4

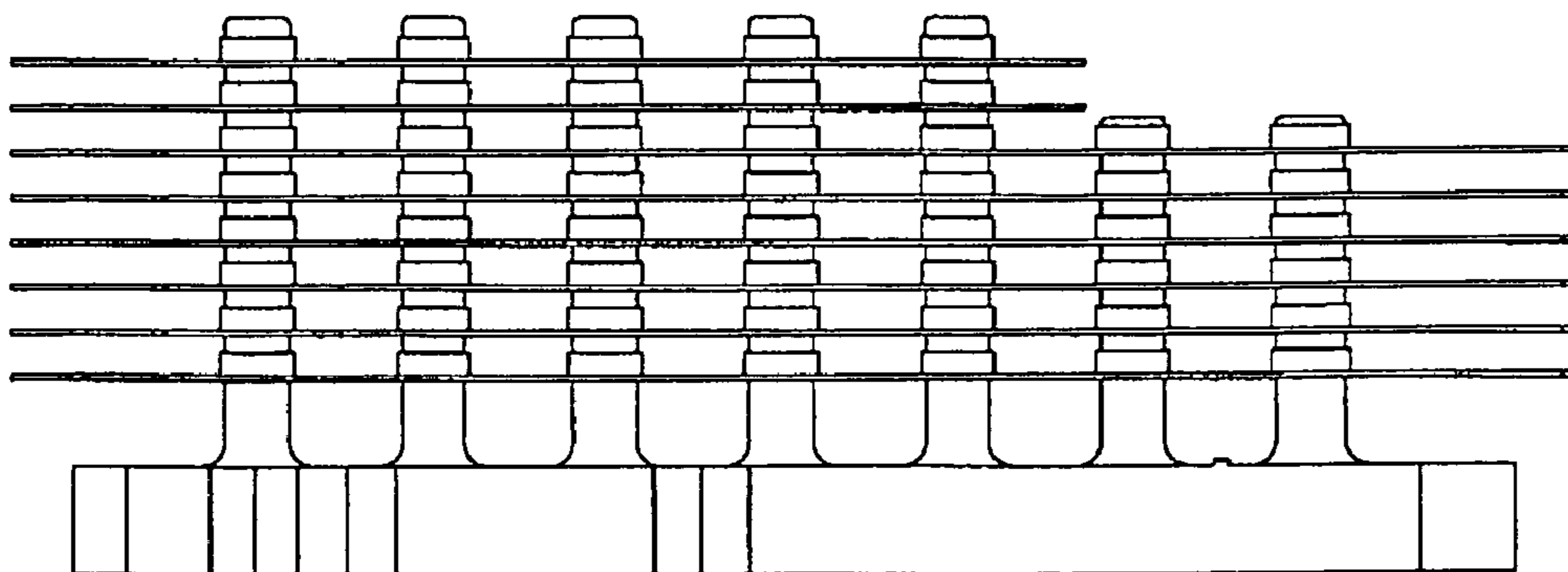


FIG. 5

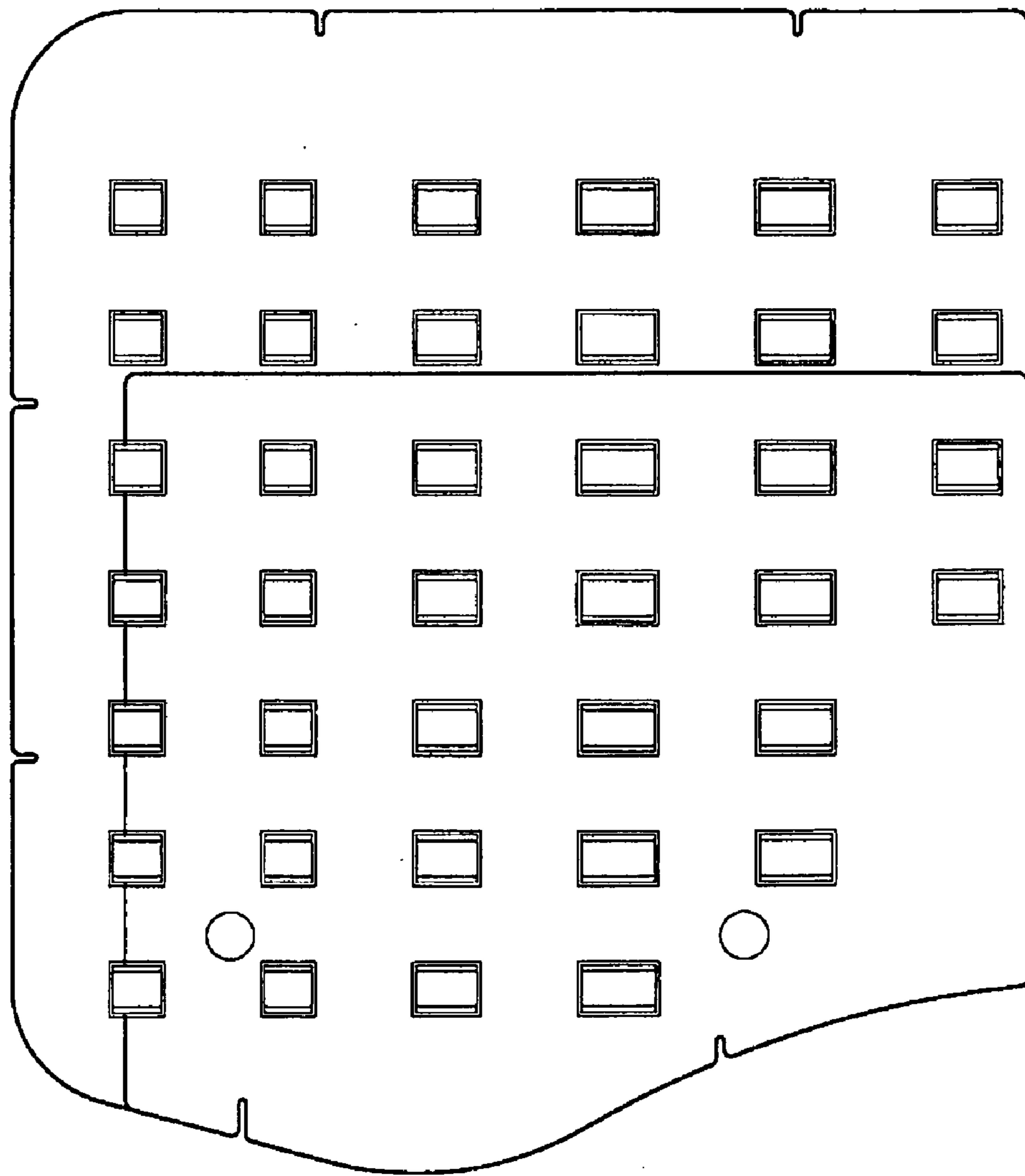


FIG. 6

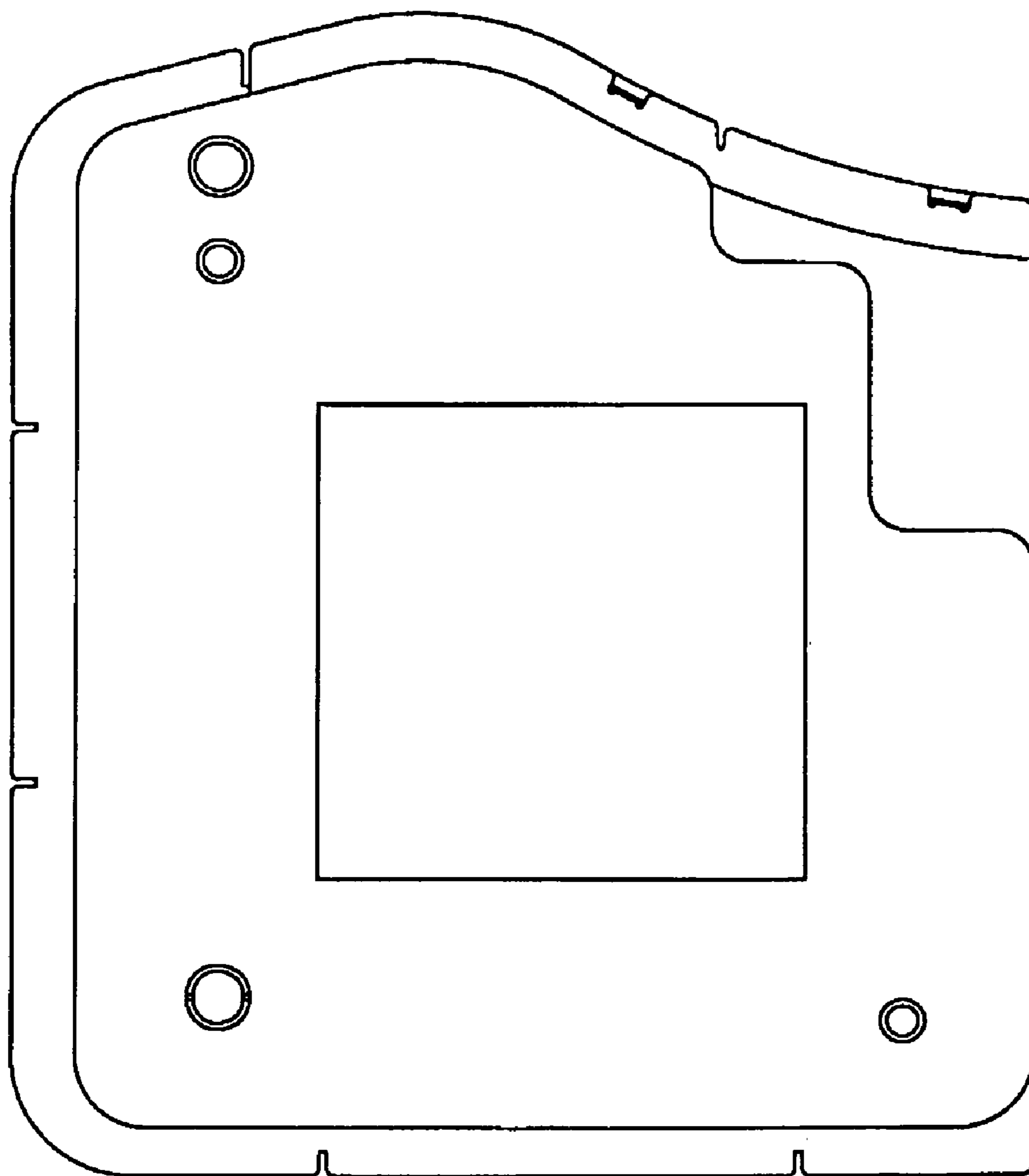


FIG. 7